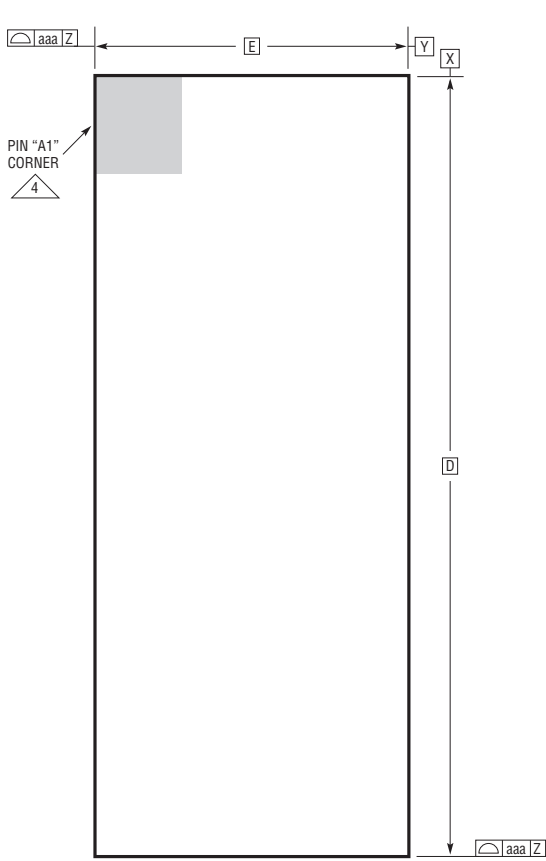
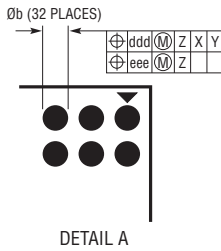
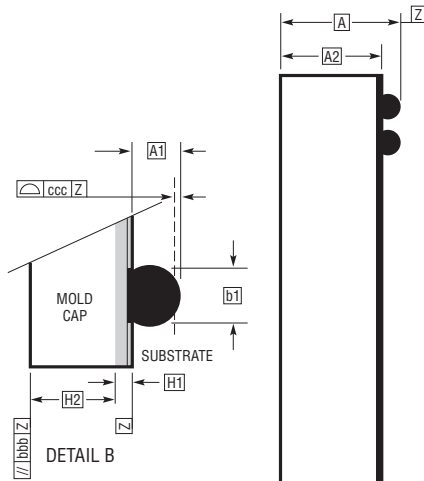


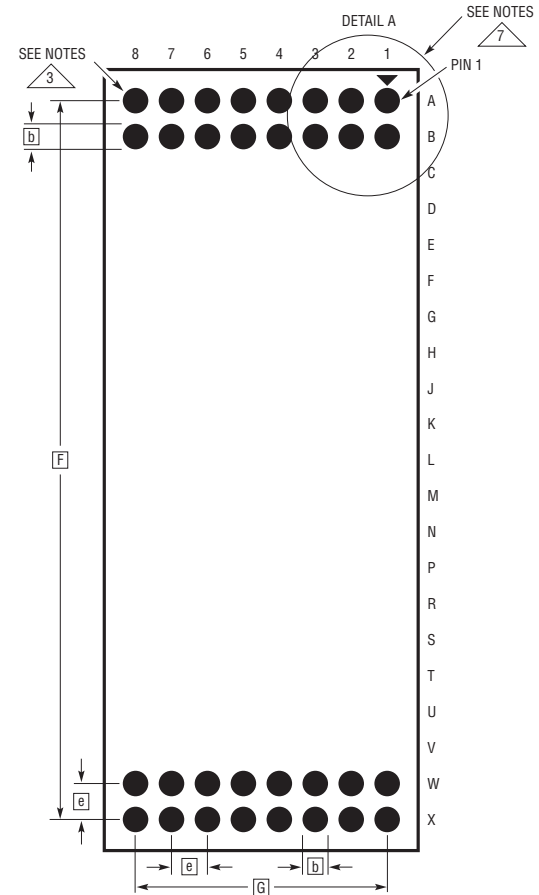
BGA Package
32-Lead (22mm × 9mm × 3.06mm)
 (Reference LTC DWG# 05-08-1975 Rev 0)



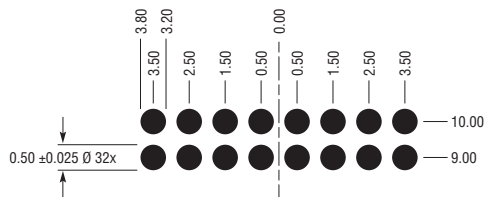
PACKAGE TOP VIEW



DETAIL B
PACKAGE SIDE VIEW



PACKAGE BOTTOM VIEW



DIMENSIONS				
SYMBOL	MIN	NOM	MAX	NOTES
A	2.81	3.06	3.31	
A1	0.40	0.50	0.60	
A2	2.41	2.56	2.71	
b	0.55	0.60	0.65	
b1	0.45	0.50	0.55	
D		22.0		
E		9.0		
e		1.0		
F		20.0		
G		7.0		
H1	0.46	0.56	0.66	
H2	1.95	2.00	2.05	
aaa			0.15	
bbb			0.10	
ccc			0.15	
ddd			0.15	
eee			0.08	

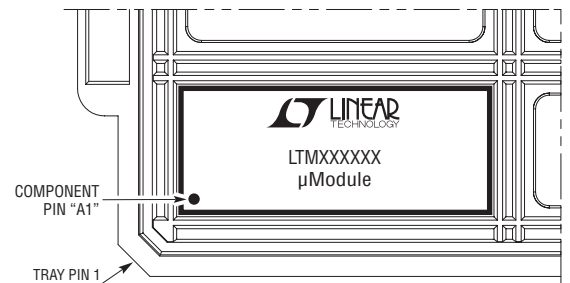
TOTAL NUMBER OF BALLS: 32



SUGGESTED PCB LAYOUT
TOP VIEW

NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994
2. ALL DIMENSIONS ARE IN MILLIMETERS
3. BALL DESIGNATION PER JESD MS-028 AND JEP95
4. DETAILS OF PIN #1 IDENTIFIER ARE OPTIONAL, BUT MUST BE LOCATED WITHIN THE ZONE INDICATED. THE PIN #1 IDENTIFIER MAY BE EITHER A MOLD OR MARKED FEATURE
5. PRIMARY DATUM -Z- IS SEATING PLANE
6. SOLDER BALL COMPOSITION IS 96.5% Sn/3.0% Ag/0.5% Cu
7. PACKAGE ROW AND COLUMN LABELING MAY VARY AMONG µModule PRODUCTS. REVIEW EACH PACKAGE LAYOUT CAREFULLY



PACKAGE IN TRAY LOADING ORIENTATION